



JIANGSU YANGJIE RUNAU SEMICONDUCTOR CO., LTD

High-end Power Semiconductor Manufacturer

CSG 30J2500

Gate turn-off Thyristor

| Features | Key Parameters | |
|---|----------------|---------|
| • Patented free-floating silicon technology | V_{DRM} | 2500 V |
| • Low on-state and switching losses | I_{TGQM} | 3000 A |
| • Annular gate electrode | I_{TSM} | 30 kA |
| • Industry standard housing | V_{TO} | 1.5 V |
| • Cosmic radiation withstand rating | r_T | 0.33 mW |
| | V_{DClink} | 1400 V |

Blocking

| | | | |
|--------------|---|---------------|--|
| V_{DRM} | Repetitive peak off-state voltage | 2500 V | $V_{GR} \geq 2V$ |
| V_{RRM} | Repetitive peak reverse voltage | 17 V | |
| I_{DRM} | Repetitive peak off-state current | ≤ 100 mA | $V_D = V_{DRM}$ $V_{GR} \geq 2V$ |
| I_{RRM} | Repetitive peak reverse current | ≤ 50 mA | $V_R = V_{RRM}$ $R_{GK} = \infty$ |
| V_{DClink} | Permanent DC voltage for 100 FIT failure rate | 1400 V | Ambient cosmic radiation at sea level in open air. |

Mechanical data (see Fig. 3)

| | | | | |
|----------------|---|--------|-----------|------------------|
| F_m | Mounting force | min. | 36 | kN |
| | | max. | 44 | kN |
| A | Acceleration: Device unclamped Device clamped | | 50 200 | m/s ² |
| M | Weight | | 1.3 | kg |
| D _S | Surface creepage distance | \geq | 33 | mm |
| D _a | Air strike distance | \geq | 15 | mm |



GTO CHARACTERISTICS

On-state

| | | | | |
|------------|--|---------------------------------------|------------------------------------|----------------------------------|
| I_{TAVM} | Max. average on-state current | 1300 A | Half sine wave, $T_C = 85^\circ C$ | |
| I_{TRMS} | Max. RMS on-state current | 2040 A | | |
| I_{TSM} | Max. peak non-repetitive surge current | 30 kA | $t_P = 10 \text{ ms}$ | $T_j = 125^\circ C$ |
| | | 51 kA | $t_P = 1 \text{ ms}$ | After surge: $V_D = V_R = 0V$ |
| I^2t | Limiting load integral | $4.5 \times 10^6 \text{ A}^2\text{s}$ | $t_P = 10 \text{ ms}$ | |
| | | $1.3 \times 10^6 \text{ A}^2\text{s}$ | $t_P = 1 \text{ ms}$ | |
| V_T | On-state voltage | 2.5 V | $I_T = 3000 \text{ A}$ | $T_j = 125^\circ C$ |
| V_{T0} | Threshold voltage | 1.5 V | $I_T = 400 - 4000 \text{ A}$ | |
| r_T | Slope resistance | 0.33 mΩ | | |
| I_H | Holding current | 100 A | $T_j = 25^\circ C$ | |

Gate

| | | | | |
|-----------|---------------------------------|-------|-----------------------|--------------------|
| V_{GT} | Gate trigger voltage | 1.2 V | $V_D = 24 \text{ V}$ | $T_j = 25^\circ C$ |
| I_{GT} | Gate trigger current | 4 A | $R_A = 0.1 \text{ W}$ | |
| V_{GRM} | Repetitive peak reverse voltage | 17 V | | |
| I_{GRM} | Repetitive peak reverse current | 50 mA | $V_{GR} = V_{GRM}$ | |

Turn-on switching

| | | | | |
|----------------|---------------------------------------|-----------|-------------------------|---|
| di/dt_{crit} | Max. rate of rise of on-state current | 500 A/μs | $f = 200\text{Hz}$ | $I_T = 3000 \text{ A}, T_j = 125^\circ C$ |
| | | 1000 A/μs | $f = 1\text{Hz}$ | $I_{GM} = 30 \text{ A}, di_G/dt = 20 \text{ A}/\mu\text{s}$ |
| t_d | Delay time | 2.5 μs | $V_D = 0.5 V_{DRM}$ | $T_j = 125^\circ C$ |
| t_r | Rise time | 5 μs | $I_T = 3000 \text{ A}$ | $di/dt = 300 \text{ A}/\mu\text{s}$ |
| $t_{on(min)}$ | Min. on-time | 100 μs | $I_{GM} = 30 \text{ A}$ | $di_G/dt = 20 \text{ A}/\mu\text{s}$ |
| E_{on} | Turn-on energy per pulse | 2 Ws | $C_s = 5 \mu\text{F}$ | $R_s = 5 \Omega$ |

Turn-off switching

| | | | | |
|-----------------------|-----------------------------------|--------|-----------------------------|---|
| I_{TGQM} | Max controllable turn-off current | 3000 A | $V_{DM} = V_{DRM}$ | $di_{GQ}/dt = 40 \text{ A}/\mu\text{s}$ |
| $C_s = 5 \mu\text{F}$ | | | $L_s \leq 0.3 \mu\text{H}$ | |
| t_s | Storage time | 25 μs | $V_D = \frac{1}{2} V_{DRM}$ | $V_{DM} = V_{DRM}$ |
| t_f | Fall time | 3 μs | $T_j = 125^\circ C$ | $di_{GQ}/dt = 40 \text{ A}/\mu\text{s}$ |
| $t_{off(min)}$ | Min. off-time | 100 μs | $I_{TGQ} = I_{TGQM}$ | |
| E_{off} | Turn-off energy per pulse | 4.7 Ws | $C_s = 5 \mu\text{F}$ | $R_s = 5 \text{ W}$ |
| I_{GQM} | Peak turn-off gate current | 1000 A | $L_s \leq 0.3 \mu\text{H}$ | |



GTO CHARACTERISTICS

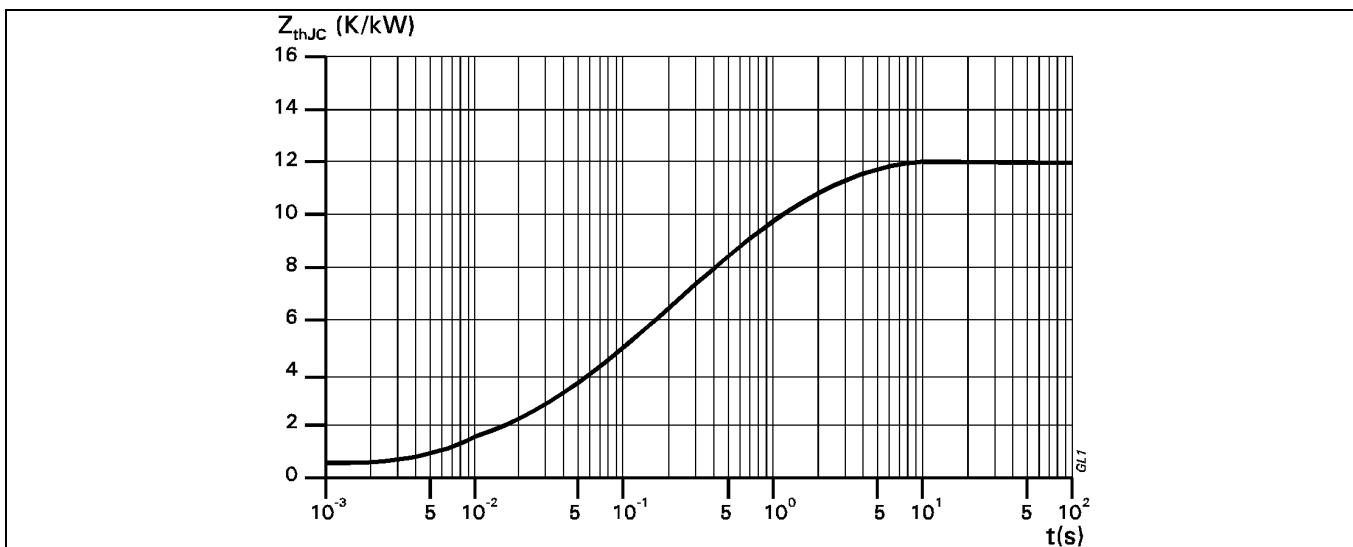
Thermal

| | | | | |
|------------|--|-------------|---------------------|--|
| T_j | Storage and operating junction temperature range | -40...125°C | | |
| R_{thJC} | Thermal resistance junction to case | 22 K/kW | Anode side cooled | |
| | | 27 K/kW | Cathode side cooled | |
| | | 12 K/kW | Double side cooled | |
| R_{thCH} | Thermal resistance case to heat sink | 6 K/kW | Single side cooled | |
| | | 3 K/kW | Double side cooled | |

Analytical function for transient thermal impedance:

$$Z_{thJC}(t) = \sum_{i=1}^4 R_i (1 - e^{-t/\tau_i})$$

| i | 1 | 2 | 3 | 4 |
|--------------|-----|------|------|-------|
| R_i (K/kW) | 5.4 | 4.5 | 1.7 | 0.4 |
| τ_i (s) | 1.2 | 0.17 | 0.01 | 0.001 |





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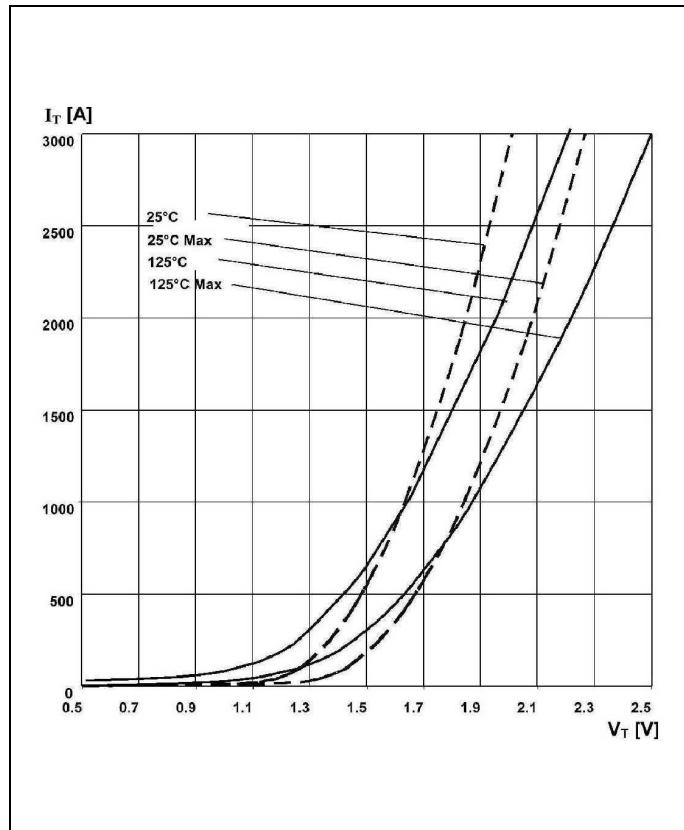


Fig. 1 On-state characteristics



GTO CHARACTERISTICS

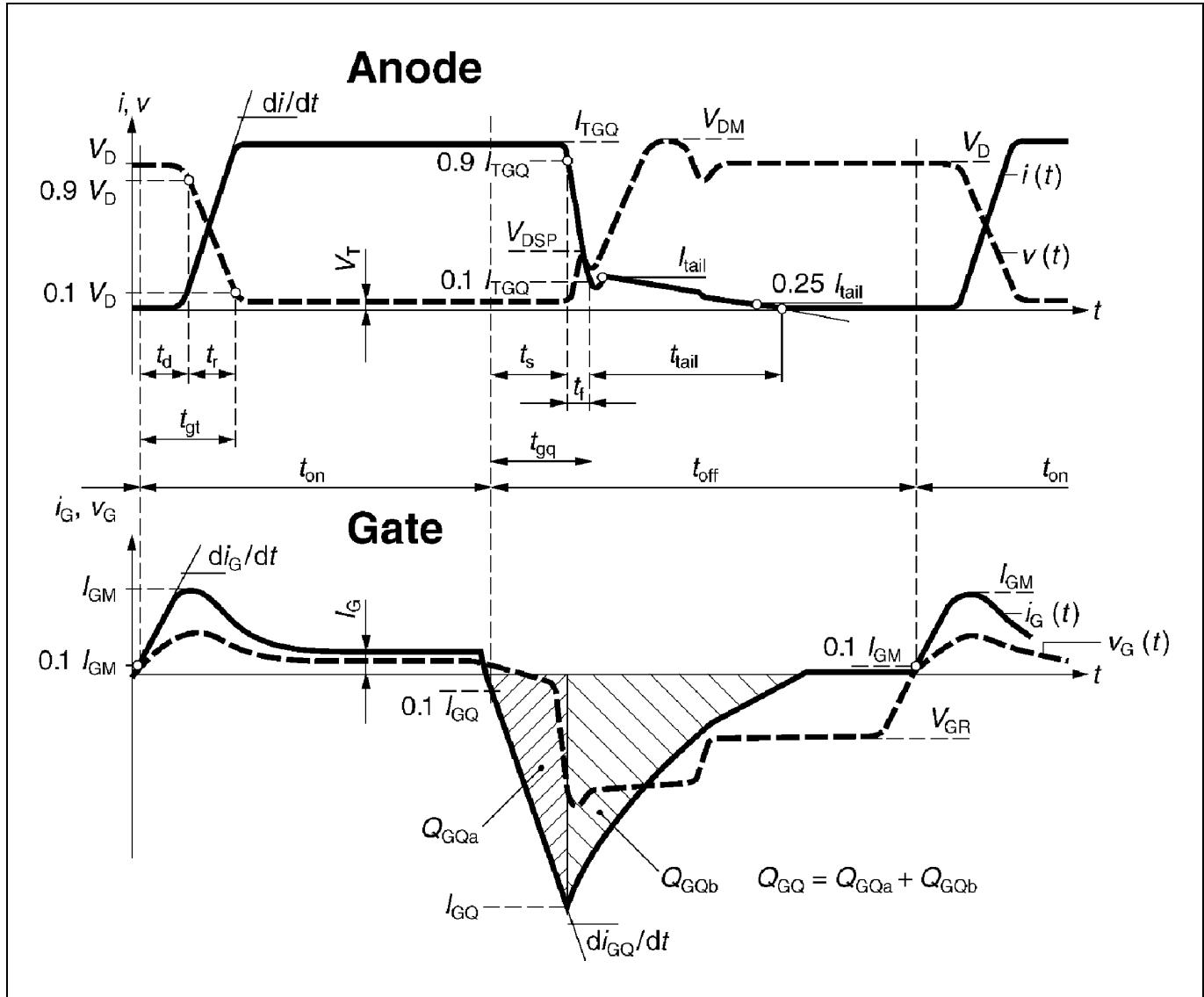


Fig. 2 General current and voltage waveforms with GTO-specific symbols



OUTLINE AND DIMENSION

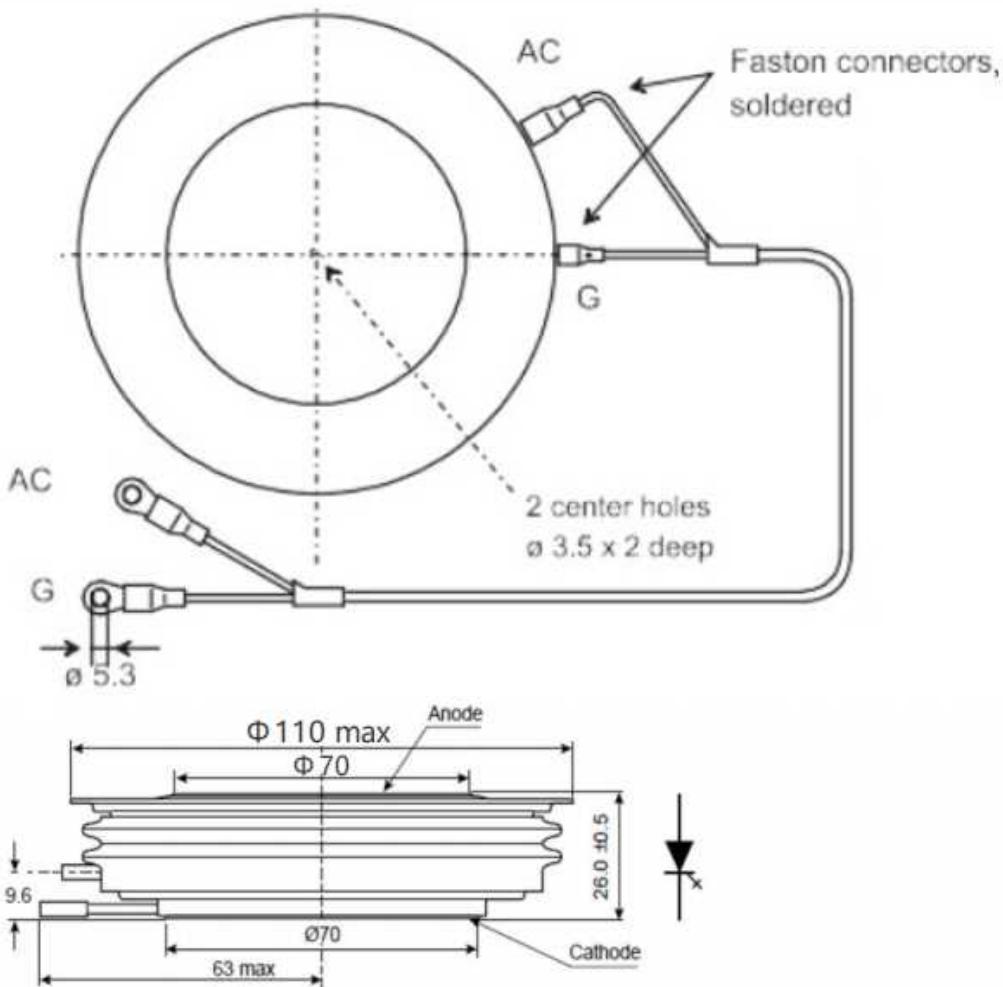


Fig. 3 Outline drawing. All dimensions are in millimeters and represent nominal val unless stated otherwise.

Reverse avalanche capability

In operation with an antiparallel freewheeling diode, the GTO reverse voltage V_R may exceed the rate value V_{RRM} due to stray inductance and diode turn-on voltage spike at high di/dt . The GTO is then driven into reverse avalanche. This condition is not dangerous for the GTO provided avalanche time and current are below 10 μs and 1000 A respectively. However, gate voltage must remain negative during this time. Recommendation : $V_{GR} = 10...15$ V.